

March 2013

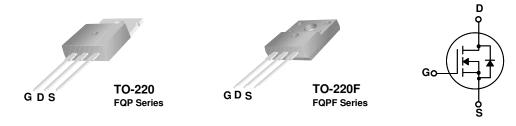
FQP6N40C / FQPF6N40C N-Channel QFET MOSFET 400 V, 6.0 A, 1.0 Ω

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- + 6.0 A, 400 V, $R_{\rm DS(on)}$ = 1.0 Ω (Max) @V $_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3.0 A
- Low Gate Charge (Typ. 16 nC)
- Low Crss (Typ. 15 pF)
- · 100% Avalanche Tested



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP6N40C	FQPF6N40C	Unit
V_{DSS}	Drain-Source Voltage		400		V
I _D	Drain Current - Continuous (T _C = 25°C)		6	6 *	Α
	- Continuous (T _C = 100°C)		3.6	3.6 *	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	24	24 *	Α
V _{GSS}	Gate-Source Voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	270		mJ
I _{AR}	Avalanche Current	(Note 1) 6		Α	
E _{AR}	Repetitive Avalanche Energy (No		7.3		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
P_D	Power Dissipation (T _C = 25°C)		73	38	W
	- Derate above 25°C		0.58	0.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300		°C

^{*} Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FQP6N40C	FQPF6N40C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.71	3.31	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	400			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		0.54		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 400 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 320 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3A		0.83	1	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_D = 3A$ (Note 4)		4.7		S
Dynam i C _{iss}	ic Characteristics Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		480	625	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		80	105	pF
C _{rss}	Reverse Transfer Capacitance	- 1.5 W. 12		15	20	pF
	ng Characteristics	,		l	l	
t _{d(on)}	Turn-On Delay Time	V 000 V I 04		13	35	ns
t _r	Turn-On Rise Time	$V_{DD} = 200 \text{ V}, I_D = 6A,$		65	140	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$		21	55	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		38	85	ns
Q _g	Total Gate Charge	$V_{DS} = 320 \text{ V}, I_{D} = 6A,$		16	20	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		2.3		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		8.2		nC
	ource Diode Characteristics a	nd Maximum Ratings				
l _S	Maximum Continuous Drain-Source Diode Forward Current				6	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				24	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 6 A			1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 6 \text{ A},$		230		ns
	<u> </u>	dl /dk 100 A/v-				

 $dI_F\,/\,dt=100\;A/\mu s$

Q_{rr}

Notes:
1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 13.7 mH, I_{AS} = 6 A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} ≤ 6A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Reverse Recovery Charge

μС

1.7

(Note 4)

Typical Characteristics

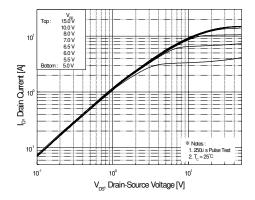


Figure 1. On-Region Characteristics

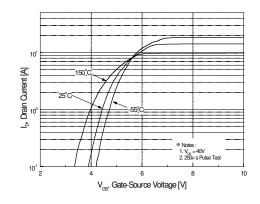


Figure 2. Transfer Characteristics

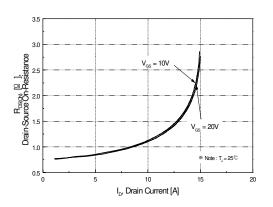


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

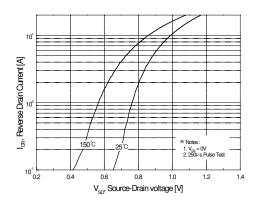


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

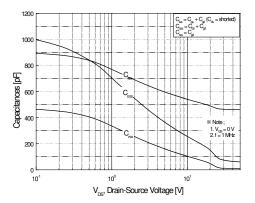


Figure 5. Capacitance Characteristics

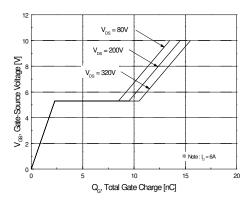


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

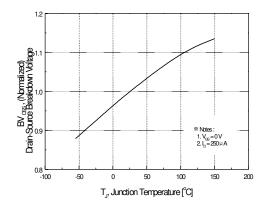


Figure 7. Breakdown Voltage Variation vs Temperature

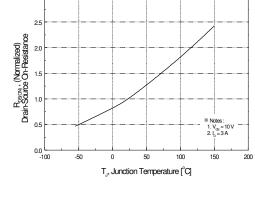


Figure 8. On-Resistance Variation vs Temperature

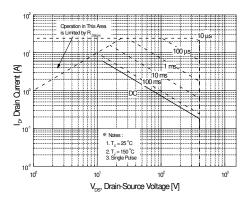


Figure 9-1. Maximum Safe Operating Area for FQP6N40C

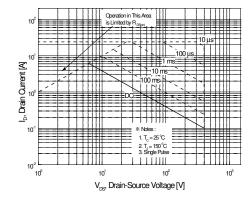


Figure 9-2. Maximum Safe Operating Area for FQPF6N40C

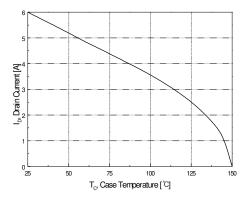


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

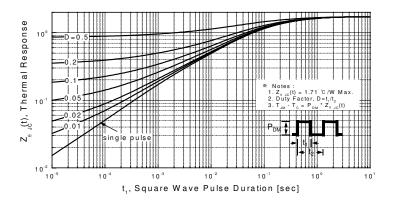


Figure 11-1. Transient Thermal Response Curve for FQP6N40C

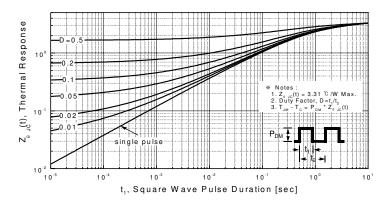
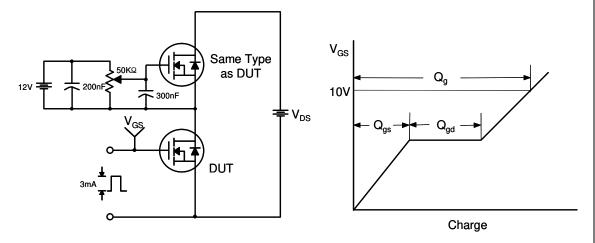
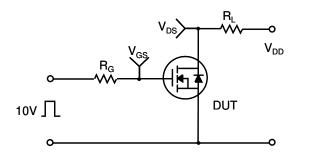


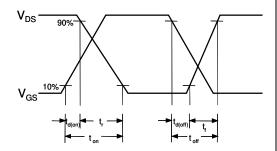
Figure 11-2. Transient Thermal Response Curve for FQPF6N40C

Gate Charge Test Circuit & Waveform

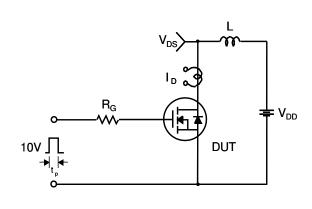


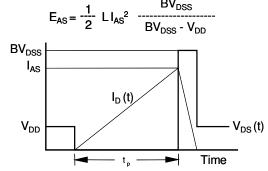
Resistive Switching Test Circuit & Waveforms



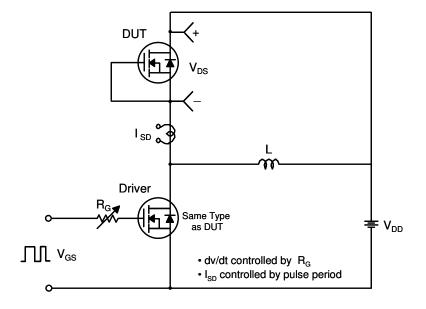


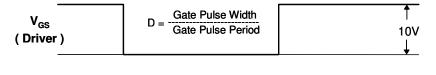
Unclamped Inductive Switching Test Circuit & Waveforms

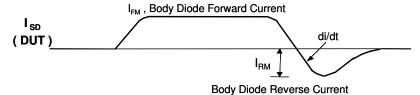


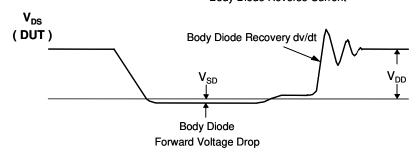


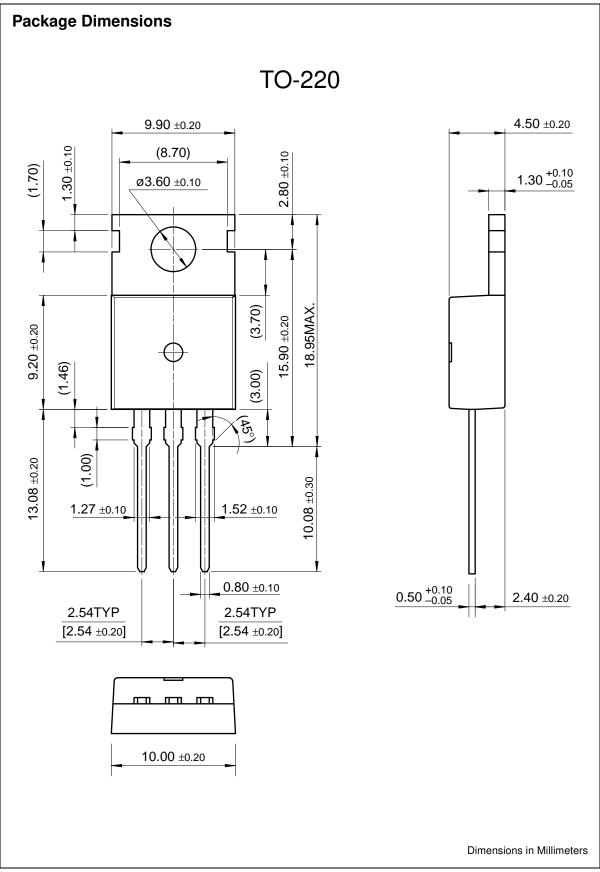
Peak Diode Recovery dv/dt Test Circuit & Waveforms

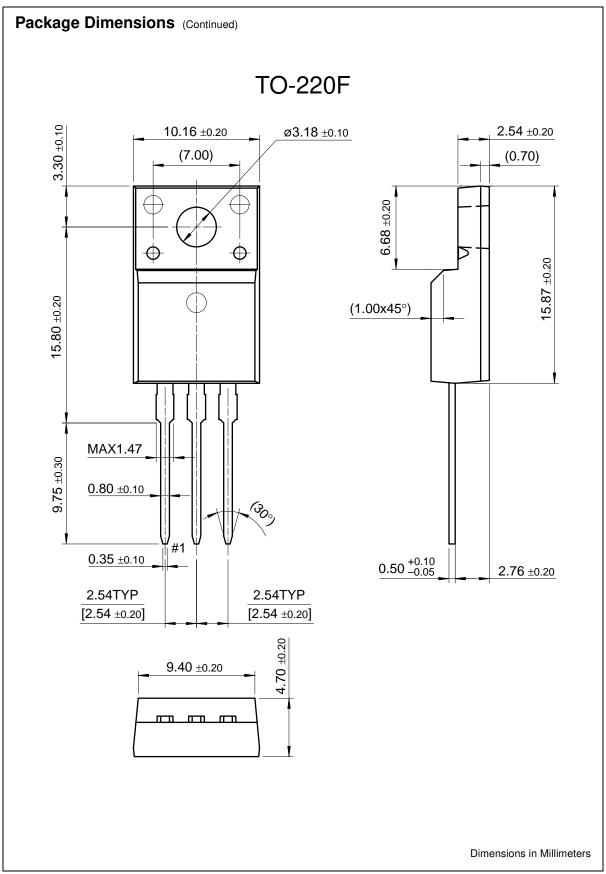
















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